
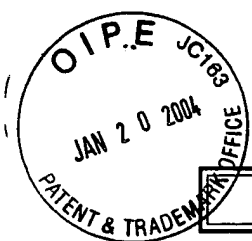


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT																																		
<p>Application Number: 09/779123 </p> <p>Confirmation Number: 9269</p> <p>First Named Applicant: Anantha Sethuraman</p> <p>Attorney Docket Number: 5298-02502</p> <p>Art Unit: 2823</p> <p>Examiner: Hsien-Ming Lee</p> <p>Search string: (5958794 or 5972124).pn.</p> <p>US Patent Documents</p> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>5958794</td><td>1999-09-28</td><td>Bruxvoort et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>5972124</td><td>1999-10-26</td><td>Sethuraman et al.</td><td></td><td></td><td></td></tr></tbody></table> <p>Signature</p> <table border="1"><thead><tr><th>Examiner Name</th><th>Date</th></tr></thead><tbody><tr><td></td><td></td></tr></tbody></table>								init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	5958794	1999-09-28	Bruxvoort et al.					2	5972124	1999-10-26	Sethuraman et al.				Examiner Name	Date		
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**FEE TRANSMITTAL**

Electronic Version v08
Stylesheet Version v08.0

Title of Invention	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT										
Application Number: 09/779123 											
Date: 2001-02-07											
First Named Applicant: Anantha R. Sethuraman											
Attorney Docket Number: 5298-02502											
Art Unit: 2823											
Examiner: Hsien-Ming Lee											
TOTAL FEE AUTHORIZED \$180											
Patent fees are subject to annual revisions on or about October 1st of each year.											
BASIC FILING FEE											
<table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
Fee Description	Fee Code	Amount \$	Fee Paid \$								
Submission Of Information Disclosure Stmt Fee	1806	180	180								
AUTHORIZED BILLING INFORMATION											
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:											
Deposit account number: 032769											
Access Code *****											
Deposit name: Conley Rose, P.C.											
Deposit authorized name: Kevin L. Daffer											
Signature: Kevin L. Daffer											
Date (YYYYMMDD): 2004-01-20											

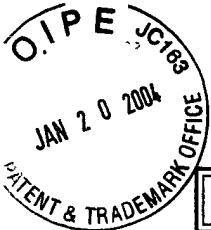


Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 53978
Application ID: 09779123
Title of Invention: PLANARIZED SEMICONDUCTOR
INTERCONNECT TOPOGRAPHY
AND METHOD FOR POLISHING A
METAL LAYER TO FORM
INTERCONNECT
First Named Inventor: Anantha Sethuraman
Domestic/Foreign Application: Domestic Application
Filing Date: 2001-02-07
Effective Receipt Date: 2004-01-20
Submission Type: Information Disclosure
Statement
Filing Type:
Confirmation number: 9269
Attorney Docket Number: 5298-02502
Total Fees Authorized: 180.0
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Deposit Account Number: 32769
Deposit Account Name: Kevin L. Daffer
Access Code: ****
RAM Payment Status: RAM success
RAM User ID: EFSPROD
RAM Accounting Date: 2004-01-20
RAM Sequence Number: 4




Digital Certificate Holder: cn=Kevin L. Daffer,ou=Registered Attorneys,ou=Patent and Trademark
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Certificate Message Digest: 9099fb8e14cf0e12f779738052769534f3ce595c



TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT															
<p>Application Number: 09/779123 </p> <p>Date: 2001-02-07</p> <p>First Named Applicant: Anantha R. Sethuraman</p> <p>Confirmation Number: 9269</p> <p>Attorney Docket Number: 5298-02502</p>																
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Kevin L. Daffer Registered Number: 34146</td><td>Kevin L. Daffer</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Kevin L. Daffer Registered Number: 34146	Kevin L. Daffer	Attorney								
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Comments
